

**Kingtronics**®**US2A THRU US2M**

**SURFACE MOUNT HIGH EFFICIENCY RECTIFIER**  
**REVERSE VOLTAGE 50 to 1000 Volts FORWARD CURRENT 2.0 Ampere**

**FEATURES**

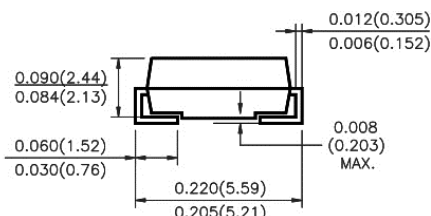
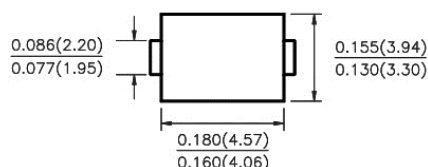
Plastic package has UL flammability  
 Classification 94V-0  
 Glass Passivated chip junction  
 Built in strain relief  
 Fast switching speed for high efficiency  
 High temperature soldering guaranteed:  
 250°C/10 seconds

**MECHANICAL DATA**

Case: JEDED DO-214AA transfer molded plastic  
 Terminals: Solder plated, Solderable per  
 MIL-STD-750, Method 2026  
 Polarity: Color band denotes cathode end

**MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS**

**Ratings at 25°C ambient temperature unless otherwise specified ,**  
**Single phase, half wave, 60Hz, resistive or inductive load.**  
**For capacitive load derate current by 20%**

**Dimensions in inches and (millimeters)**

PARAMETER	SYMBOL	US2A	US2B	US2D	US2G	US2J	US2K	US2M	UNIT
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	50	100	200	400	600	800	1000	VOLTS
Maximum RMS Voltage	$V_{RMS}$	35	70	140	280	420	560	700	VOLTS
Maximum DC Blocking Voltage	$V_{DC}$	50	100	200	400	600	800	1000	VOLTS
Maximum Average Forward Rectified Current At $T_L=105^\circ\text{C}$ (NOTE 1)	$I_{(AV)}$	2.0							Amps
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$	50							Amps
Maximum instantaneous forward voltage at 2.0A	$V_F$	1.0		1.3		1.7		VOLTS	
Maximum DC Reverse Current at Rated DC blocking voltage	$I_R$	$T_A=25^\circ\text{C}$							uA
		5.0							
Maximum Reverse Recovery Time Test conditions $I_F=0.5\text{A}$ , $I_R=1.0\text{A}$ , $I_{RR}=0.25\text{A}$	$t_{rr}$	50			100				ns
		$T_A=125^\circ\text{C}$							
Typical Junction Capacitance(Measured at 1.0MHz and applied reverse voltage of 4.0V)	$C_J$	50			30				pF
Typical Thermal Resistance (NOTE 1)	$R_{\theta JA}$	75							°C/W
	$R_{\theta JL}$	17							
Operating Junction Temperature	$T_J$	-55 to +150							°C
Storage Temperature Rang	$T_{STG}$	-55 to +150							°C

1- Thermal resistance from Junction to ambient and from junction to lead mounted on P.C.B. with  $0.3 \times 0.3''$  ( $8.0 \times 8.0\text{mm}$ ) copper pad areas

**Kingtronics**® International Company

## RATINGS AND CHARACTERISTIC CURVES

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

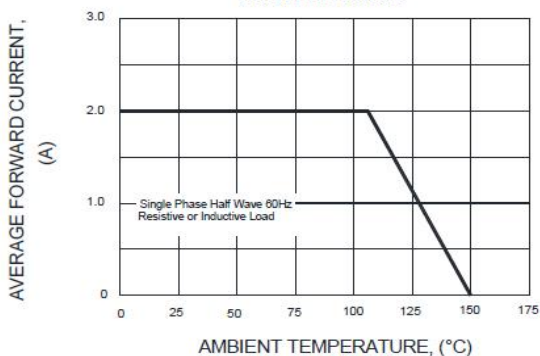


FIG.2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

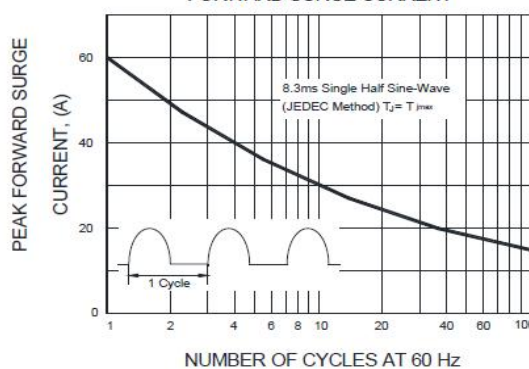


FIG.3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

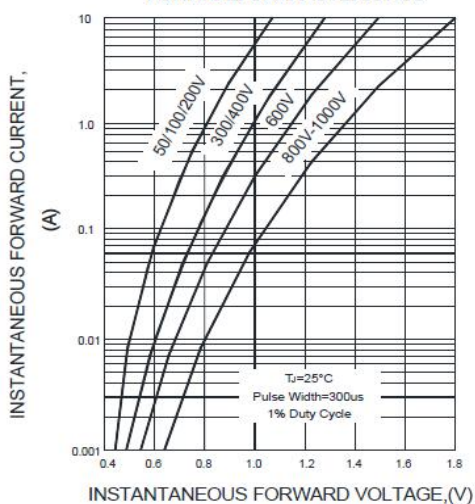


FIG.4-TYPICAL REVERSE CHARACTERISTICS

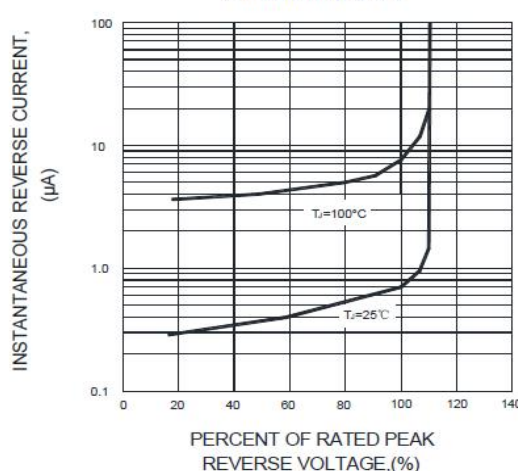


FIG.5-TYPICAL JUNCTION CAPACITANCE

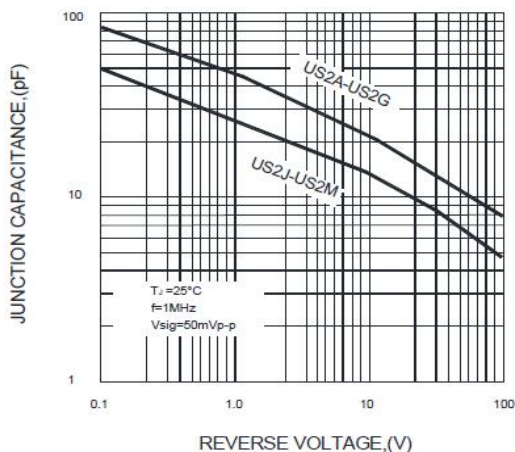
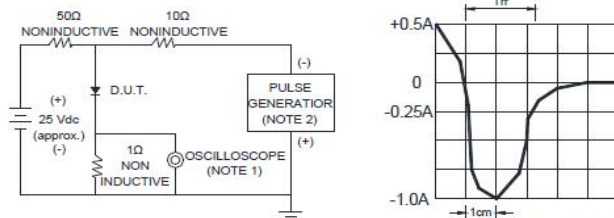


FIG.6-TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTIC



NOTES: 1. Rise Time = 7ns max. Input Impedance = 1 magohm. 22pF  
2. Rise time = 10ns max. Source Impedance = 50 ohms

SET TIME BASE FOR 50/100ns/cm

Note: Specifications are subject to change without notice.